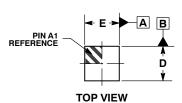
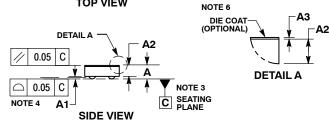
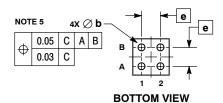


WLCSP4, 0.77x0.77 CASE 567PB **ISSUE A**

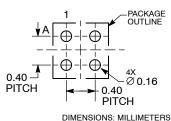
DATE 09 NOV 2016







RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- T 14.3M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
 DATUM C, THE SEATING PLANE, IS DEFINED BY THE
 SPHERICAL CROWNS OF THE SOLDER BALLS.
 COPLANARITY APPLIES TO SPHERICAL CROWNS OF
- THE SOLDER BALLS.
- DIMENSION 6 IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
- 6. BACKSIDE COATING IS OPTIONAL.

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α			0.30	
A1	0.04	0.055	0.07	
A2		0.19 REF		
A3	0.025 REF			
b	0.15	0.155	0.16	
D	0.75	0.77	0.79	
E	0.75	0.77	0.79	
е		0.40 BSC	;	

GENERIC MARKING DIAGRAM*



= Specific Device Code

= Year

W = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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